

**CHIP-PACKAGING WITH BONDING OPTIONS HAVING A PLURALITY OF  
PACKAGE SUBSTRATES**

|              |   |                    |                  |      |
|--------------|---|--------------------|------------------|------|
| Appl. No.    | : | 10/709,427         | Confirmation No. | 3426 |
| Applicant    | : | Cheng-Yen<br>Huang |                  |      |
| Filed        | : | May 5, 2004        |                  |      |
| TC/A.U.      | : | 2822               |                  |      |
| Examiner     | : | Prenty, Mark V     |                  |      |
| Docket No.   | : | FTCP0036USA0       |                  |      |
| Customer No. | : | 27765              |                  |      |

Commissioner for Patents  
P.O. Box 1450  
Alexandria VA 22313-1450

**AMENDMENT**

5 Sir:

In response to the Office action of August 03, 2006, please amend the above-identified application as follows:

**Amendments to the Claims** are reflected in the listing of claims which begins on page 2 of this paper.

10 **Remarks/Arguments** begin on page 4 of this paper.